

Size $8.3 \times 7.5 \times 5.5$ (mm)

Series/Type: B82473A1

Date: March 2008

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B82473A1

Size $8.3 \times 7.5 \times 5.5$ (mm)

SMD

Rated inductance 10 μ H to 470 μ H Rated current 0.34 A to 2.3 A

Construction

- Ferrite core
- Winding: enamel copper wire
- Winding soldered to terminals
- Plastic terminal carrier

Features

- Temperature range up to 150 °C
- High rated current
- Low DC resistance
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020C
- Qualification based on AEC-Q200
- RoHS-compatible

Applications

- Filtering of supply voltages
- Coupling, decoupling
- DC/DC converters
- Automotive electronics
- Industrial electronics
- Consumer electronics

Terminals

- Base material CuSn6P
- Layer composition Ni, Sn (lead-free)
- Electro-plated

Marking

- Marking on component:
 L value (μH, coded),
 manufacturing date (YWWD)
- Minimum data on reel: Manufacturer, ordering code, L value, quantity, date of packing

Delivery mode and packing unit

- 16-mm blister tape, wound on 330-mm \varnothing reel
- Packing unit: 1000 pcs./reel



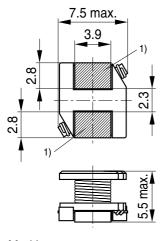


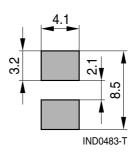
B82473A1

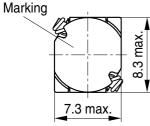
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Dimensional drawing and layout recommendation







1) Soldering area

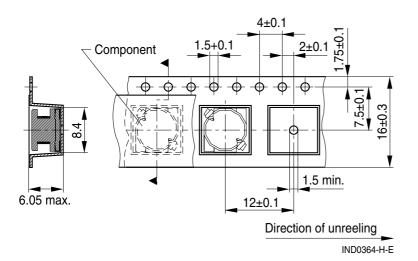
IND0482-K-E

Dimensions in mm

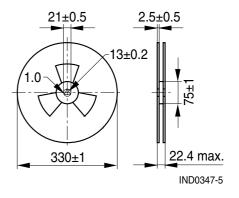
Component tolerances ± 0.2 mm unless otherwise noted.

Taping and packing

Blister tape



Reel



Dimensions in mm



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Technical data and measuring conditions

Rated inductance L _R	Measured with LCR meter Agilent 4284A frequency f _L , 0.1 V, 20 °C			
Rated temperature T _R	85 °C			
Rated current I _R	Max. permissible DC with temperature increase of \leq 40 K at rated temperature			
Saturation current I _{sat}	Max. permissible DC with inductance decrease $\Delta L/L_0$ of approx. 10%			
DC resistance R _{max}	Measured at 20 °C			
Solderability (lead-free)	Dip and look method Sn95.5Ag3.8Cu0.7: (245 ± 5) °C, (5 ± 0.3) s Wetting of soldering area $\geq 90\%$ (based on IEC 60068-2-58)			
Resistance to soldering heat	260 °C, 40 s (as referenced in JEDEC J-STD 020C)			
Climatic category	55/150/56 (to IEC 60068-1)			
Storage conditions	Mounted: -55 °C +150 °C Packaged: -25 °C +40 °C, ≤ 75% RH			
Weight	Approx. 1.5 g			

Characteristics and ordering codes

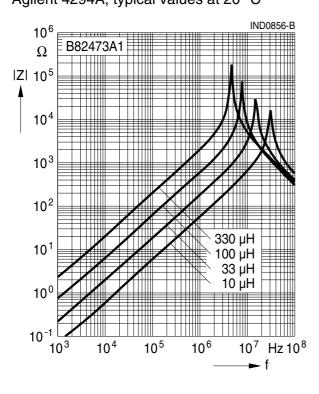
L _R	Tolerance	fL	I _R	I _{sat}	R _{max}	Ordering code
μΗ		MHz	Α	Α	Ω	
10	±10% ≙ K	0.1	2.30	2.50	0.07	B82473A1103K000
15		0.1	1.80	2.00	0.09	B82473A1153K000
22		0.1	1.50	1.60	0.11	B82473A1223K000
33		0.1	1.20	1.30	0.13	B82473A1333K000
47		0.1	1.10	1.20	0.18	B82473A1473K000
68		0.1	0.85	0.90	0.28	B82473A1683K000
100		0.1	0.72	0.80	0.43	B82473A1104K000
150		0.1	0.58	0.65	0.64	B82473A1154K000
220		0.1	0.49	0.55	0.96	B82473A1224K000
330		0.1	0.40	0.45	1.26	B82473A1334K000
470		0.1	0.34	0.40	1.96	B82473A1474K000

Sample kit available. Ordering code: B8247XX001 For more information refer to chapter "Sample kits".

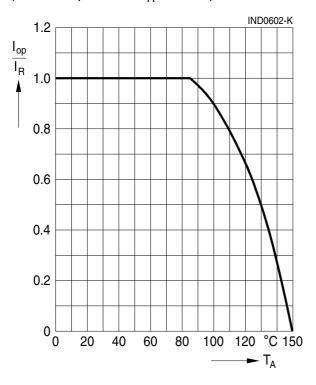


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Impedance IZI versus frequency f measured with impedance analyzer Agilent 4294A, typical values at 20 °C

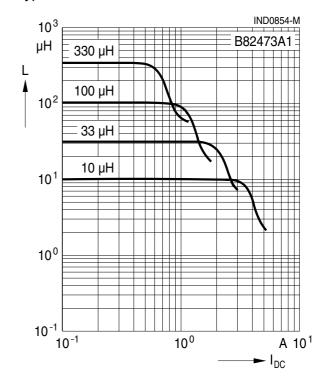


Current derating I_{op}/I_R versus ambient temperature T_A (rated temperature $T_R = 85$ °C)



SMD

Inductance L versus DC load current I_{DC} measured with LCR meter, Agilent 4275A, typical values at 20 °C





Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.



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